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(12) **United States Design Patent**  
**Kanda et al.**

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(54) **SEMICONDUCTOR MODULE**

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- (\*\*) Term: **15 Years**
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**Related U.S. Application Data**

- (62) Division of application No. 29/666,024, filed on Oct. 9, 2018, now Pat. No. Des. 906,271.

(30) **Foreign Application Priority Data**

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- Apr. 13, 2018 (JP) ..... 2018-008229

- (51) **LOC (14) Cl.** ..... **13-03**

- (52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**

- USPC ..... D13/182; 257/678, 684, 690, 691; 361/679.01, 713, 728, 736, 760, 761, 772, 361/775, 783, 820; 174/250, 253; 438/15, 25, 26, 51, 55, 63, 64, 106
- CPC . H01L 21/00; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/02; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L

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(57) **CLAIM**

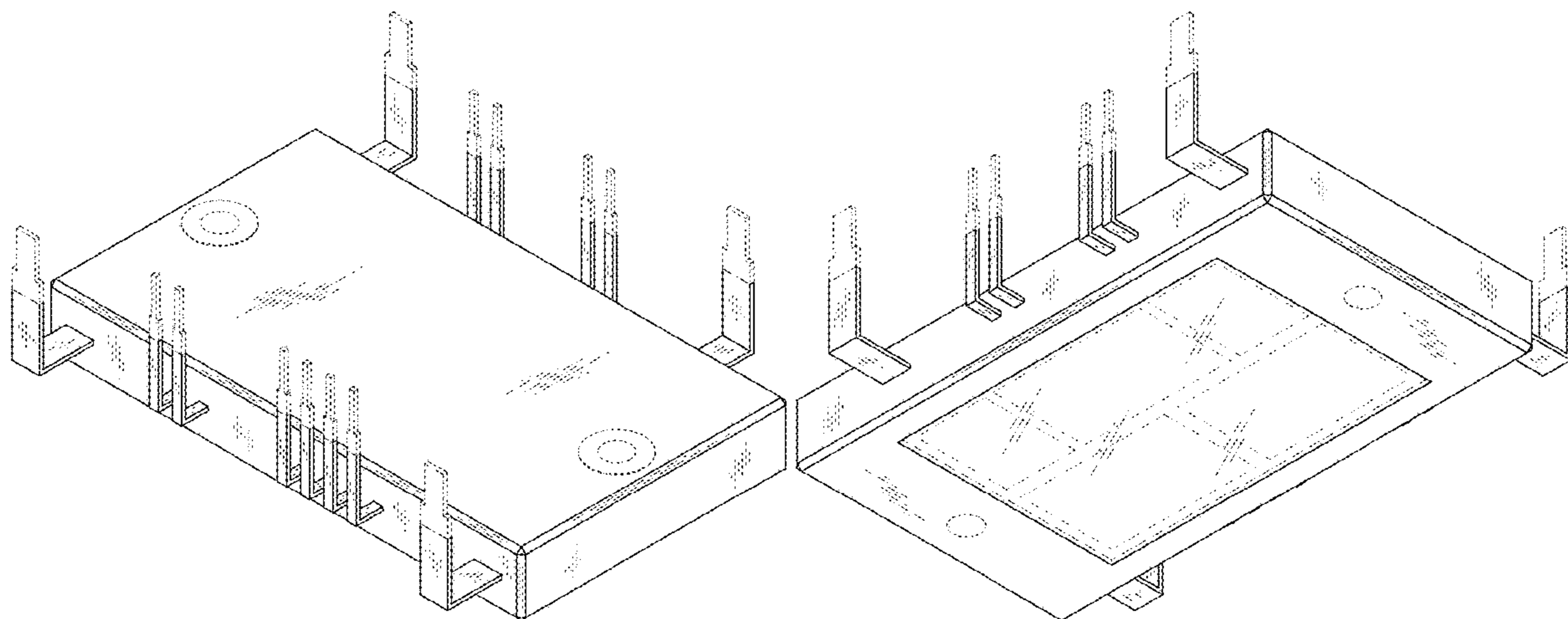
The ornamental design for a semiconductor module, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top and right side perspective view of a semiconductor module, showing our new design;  
 FIG. 2 is a rear, bottom, and left side perspective view thereof;  
 FIG. 3 is a front view thereof;  
 FIG. 4 is a rear view thereof;  
 FIG. 5 is a top plan view thereof;  
 FIG. 6 is a bottom plan view thereof;  
 FIG. 7 is a right side view thereof, the left side view being identical to FIG. 7;  
 FIG. 8 is a cross-sectional view taken along line 8-8 in FIG. 5; and,  
 FIG. 9 is a cross-sectional view taken along line 9-9 in FIG. 5.

The even broken lines illustrate portions of the semiconductor module and form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design. The member illustrated with fine, diagonal, parallel lines in FIG. 2 and FIG. 6 is transparent.

**1 Claim, 9 Drawing Sheets**



(58) **Field of Classification Search**

CPC ..... 2924/17151; H01L 2924/181; H01L  
2924/1811; H01L 2924/1815; H01L  
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2224/08054; H01L 23/58; H05B 41/14;  
G02B 6/4201; G02B 6/4256; G02B  
6/4257; G02B 6/4261; G02B 6/4262;  
G02B 6/428; G02B 6/4281; H05K 1/14;  
H05K 1/141; H05K 1/142; H05K 1/144;  
H05K 1/18; H05K 1/181; H05K 1/182;  
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See application file for complete search history.

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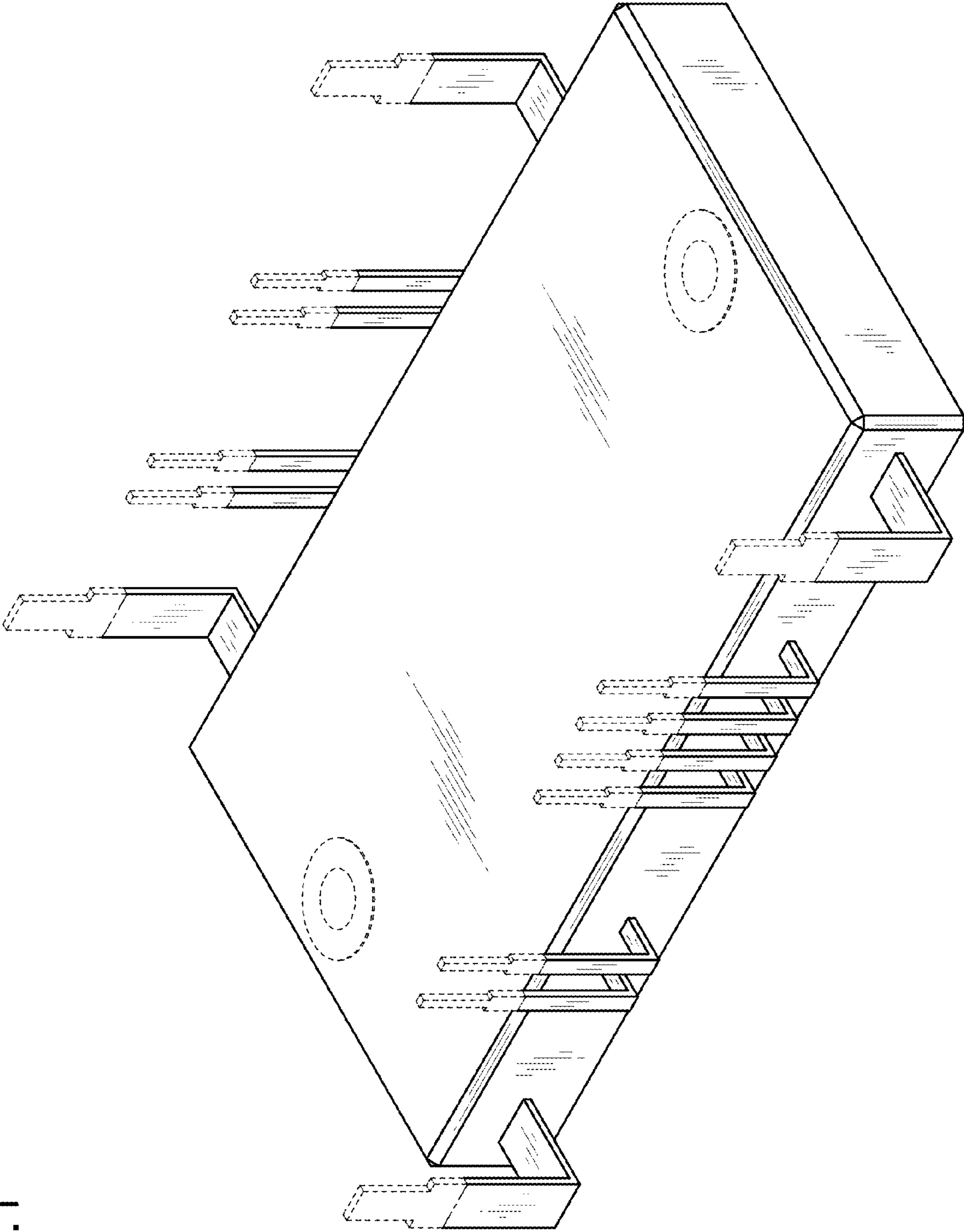


FIG.1

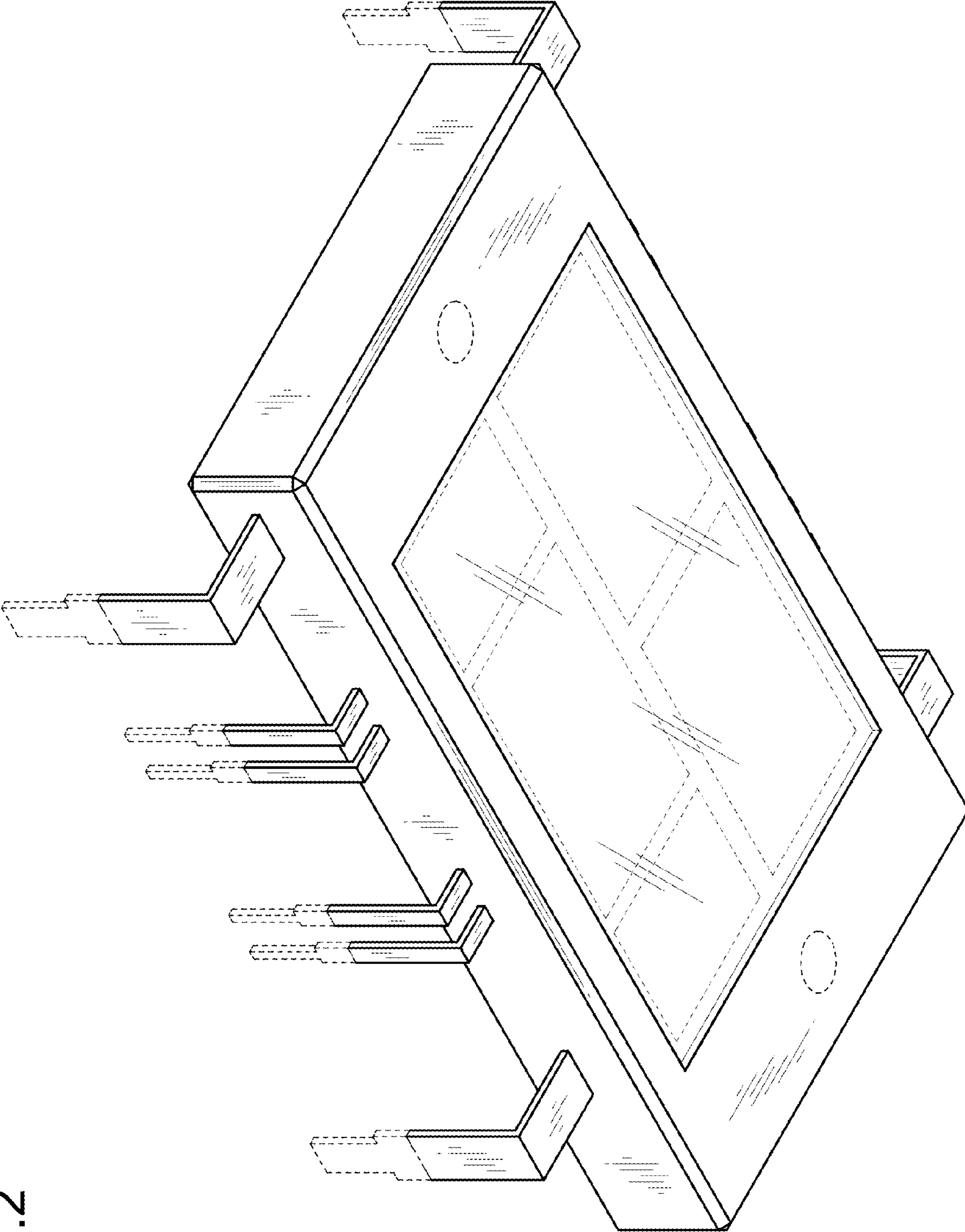


FIG.2

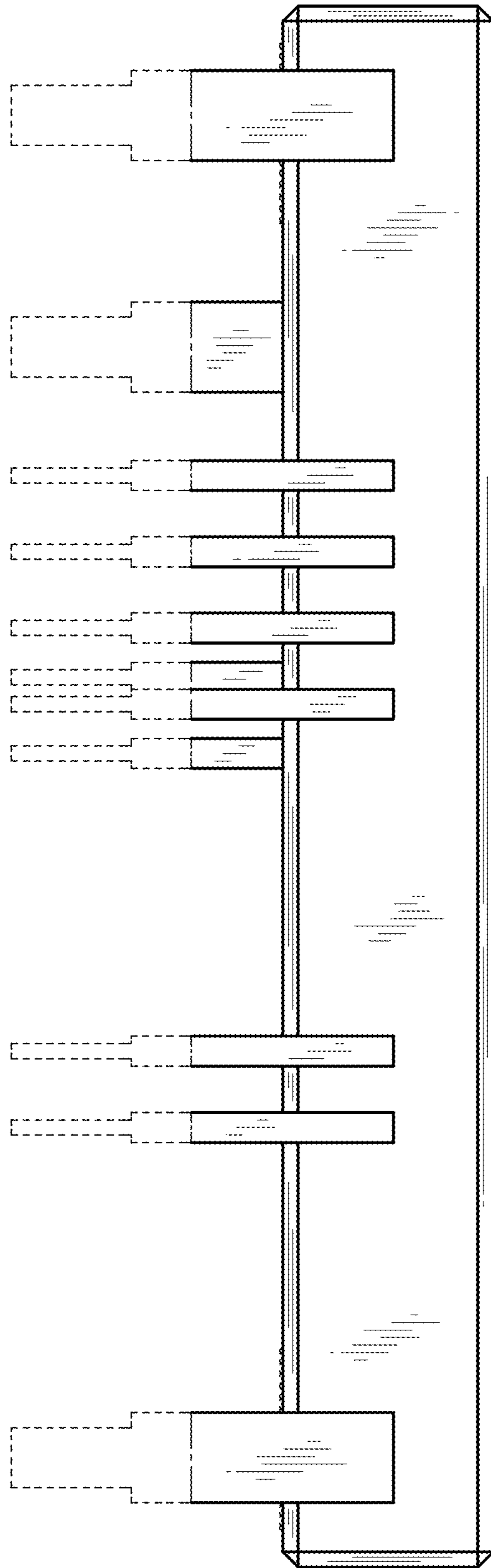


FIG.3

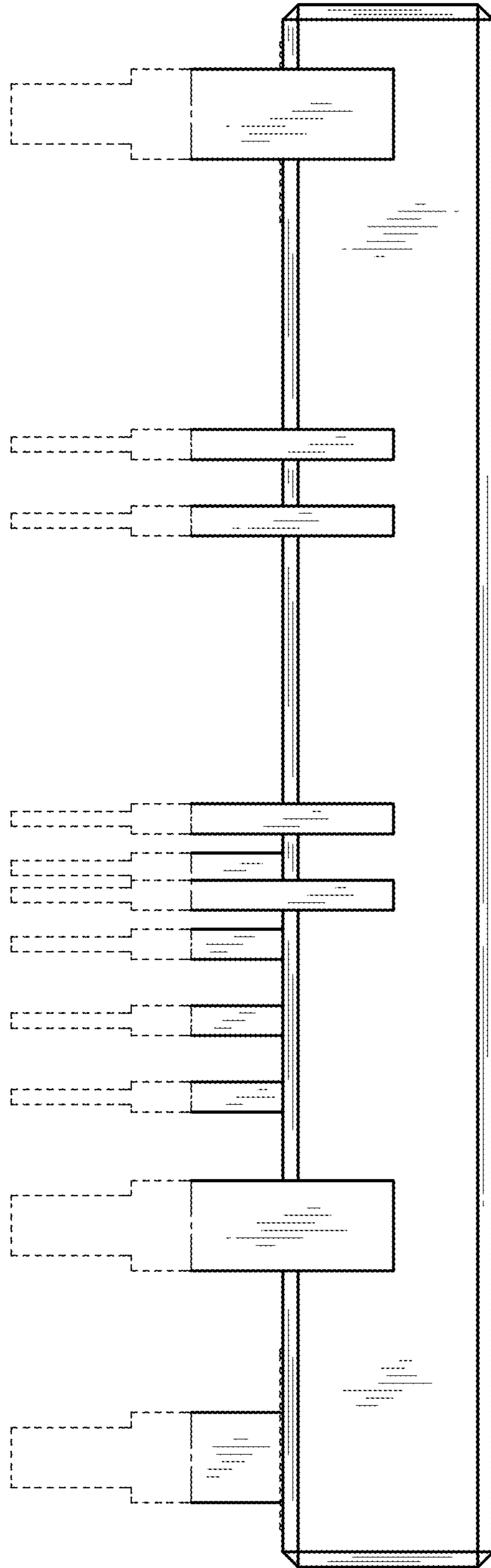


FIG.4

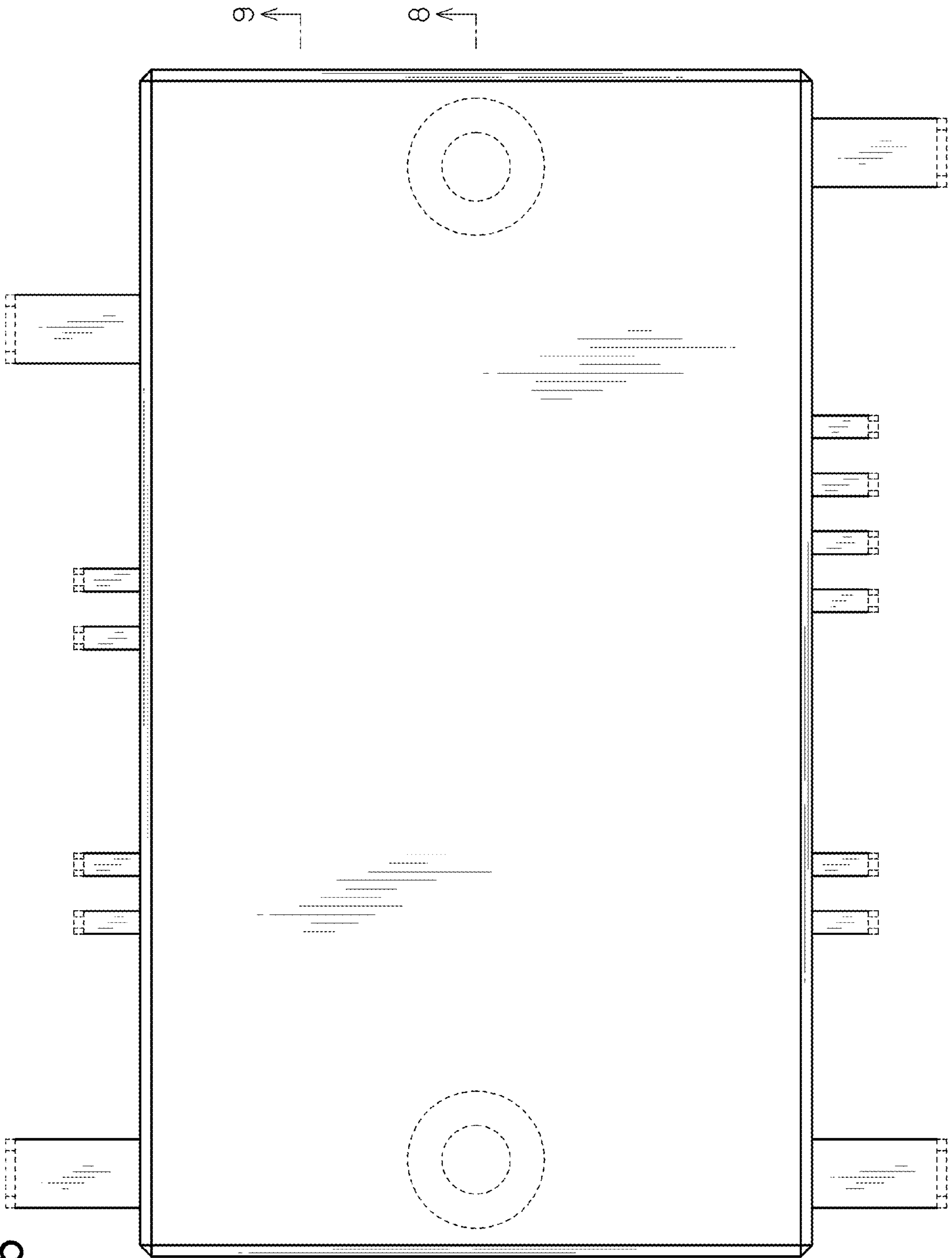


FIG.5

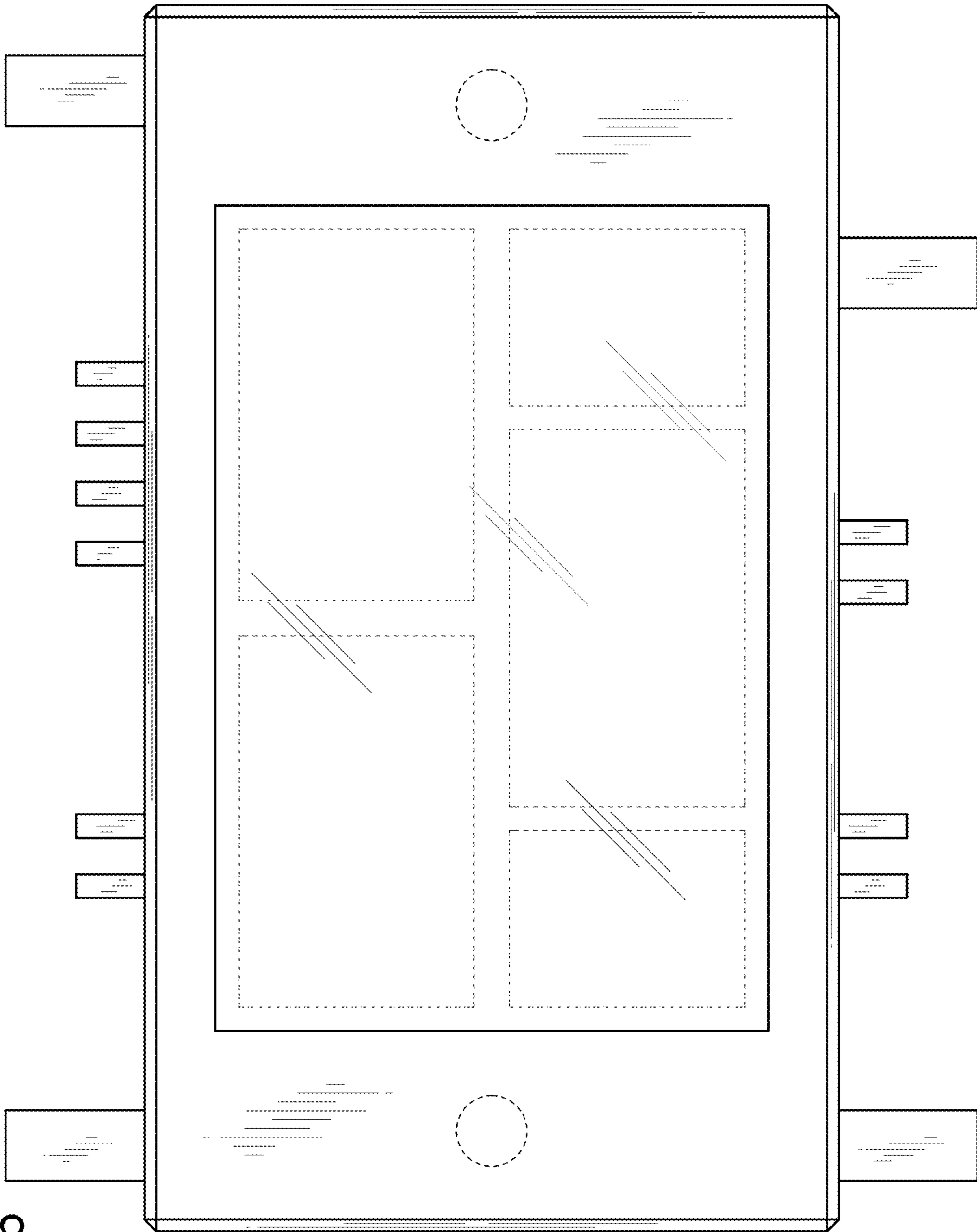


FIG. 6



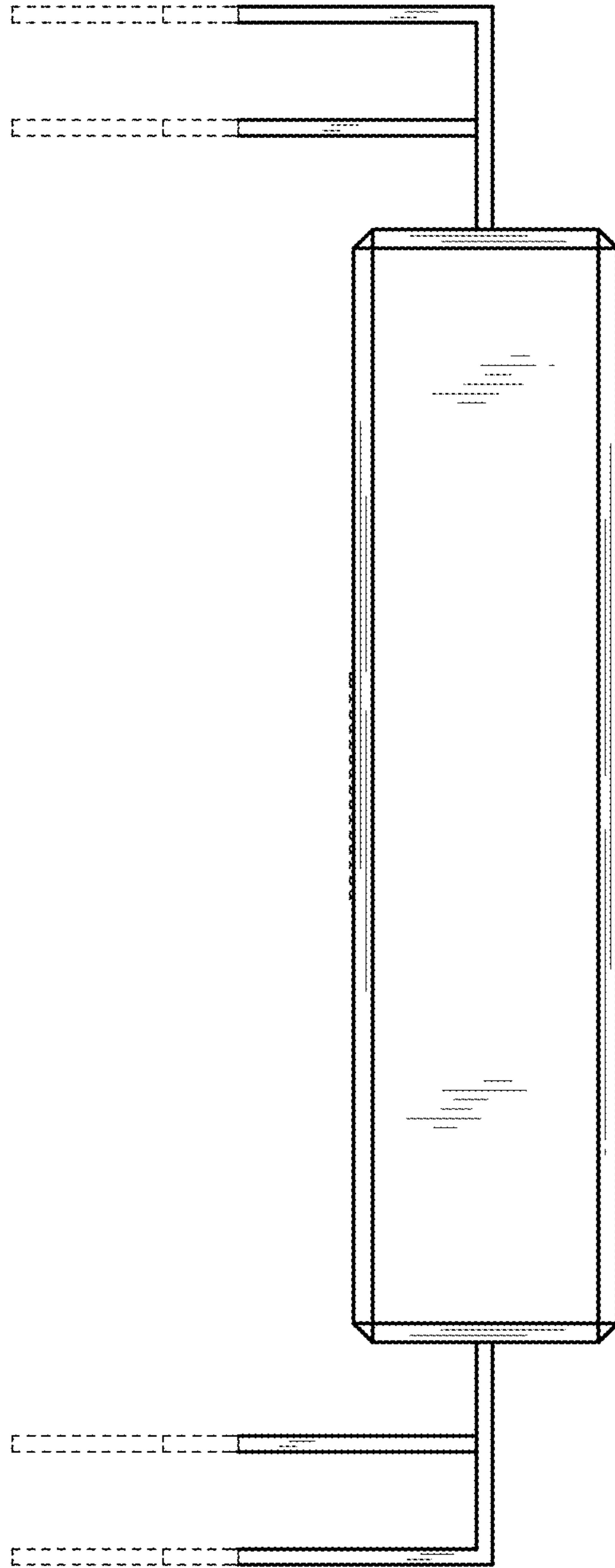
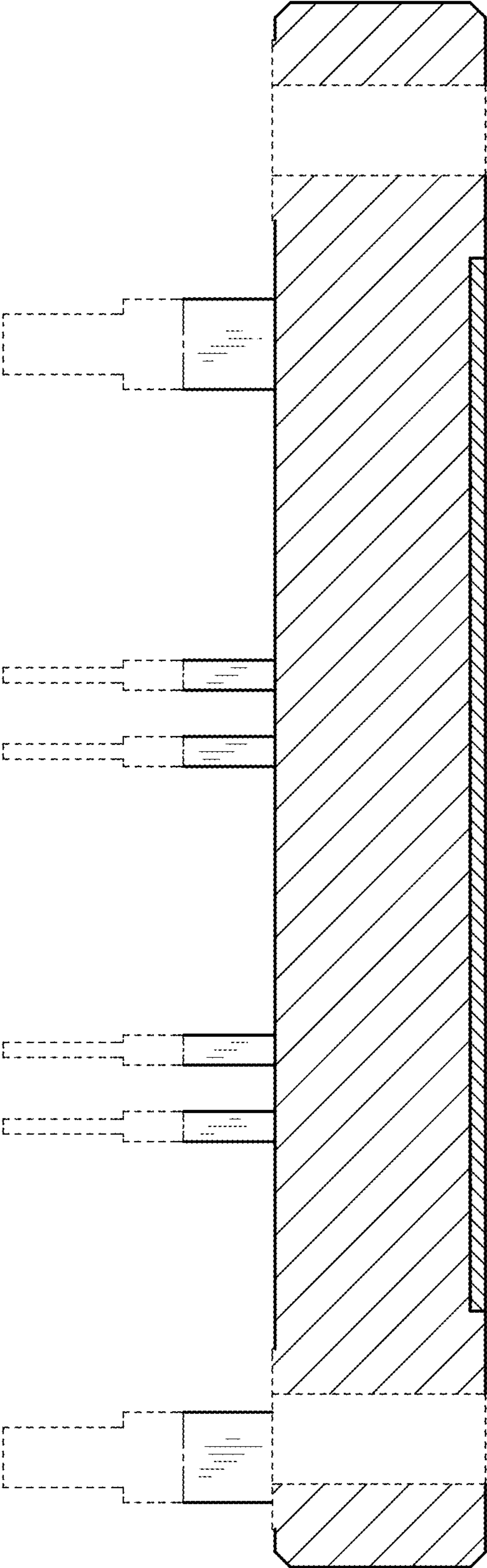


FIG.7

FIG. 8



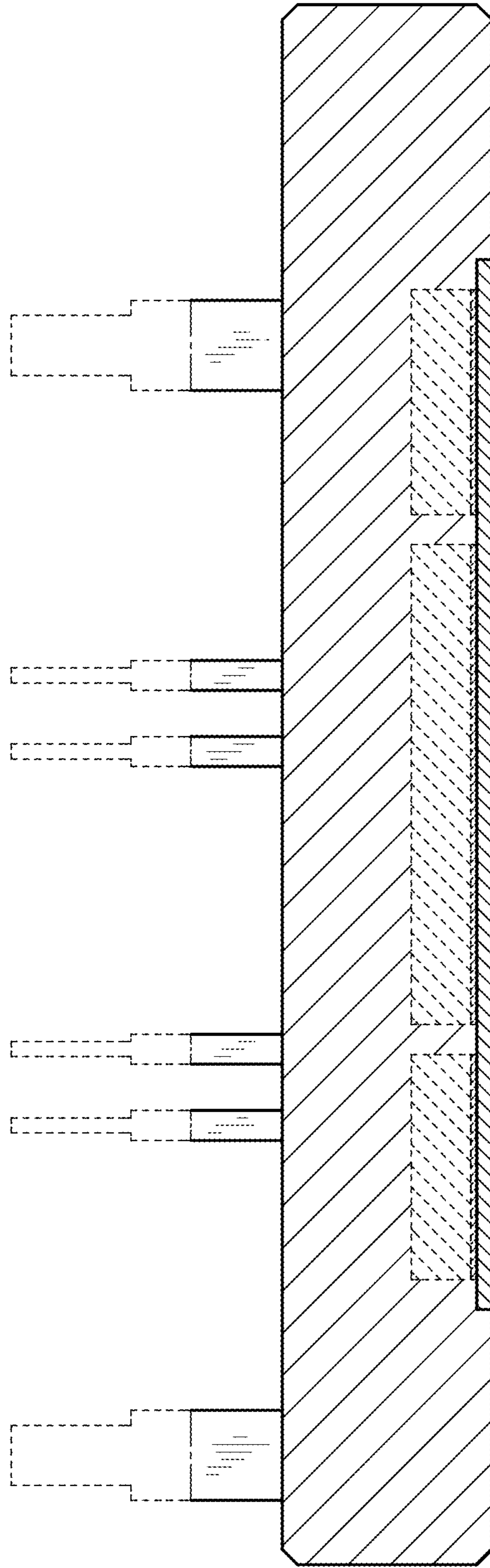


FIG.9